

フレキシブル基板対応無電解ニッケルめっき液

ICPニコロンFPF-X

Electroless Ni plating process for Flexible PWBs

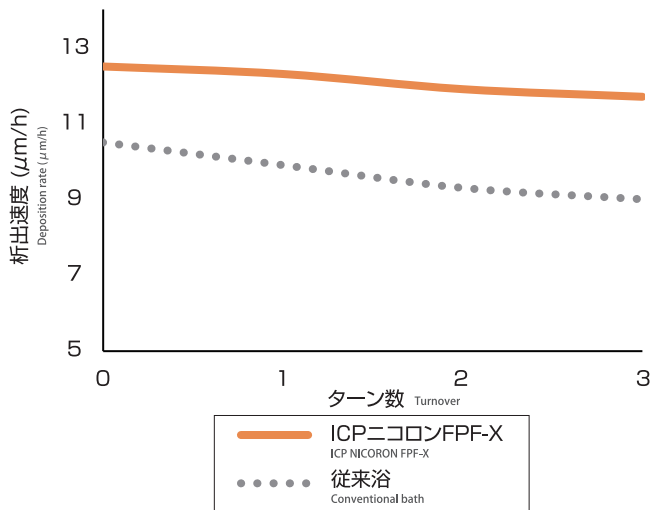
ICP NICORON FPF-X

- ニッケルめっき析出性に優れる
- 良好なはんだ接合強度が得られる
- 耐折性に優れた皮膜が得られる
- 耐食性に優れた皮膜が得られる

- Excellent in nickel plating performance
- Excellent in solder joint performance
- Excellent in folding endurance performance
- Excellent in corrosion resistance

良好なめっき析出性

High deposition performance



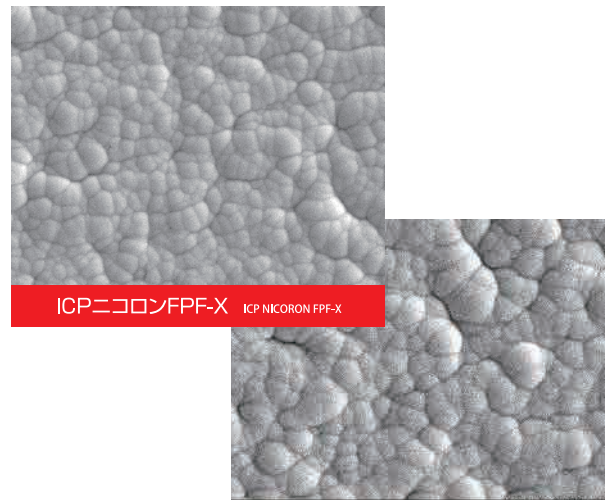
連続使用時における析出速度
Deposition speed in continuous use

従来浴よりも優れためっき析出性

Improve fine plating performance

耐食性の向上

Improve corrosion resistance



従来浴 Conventional bath

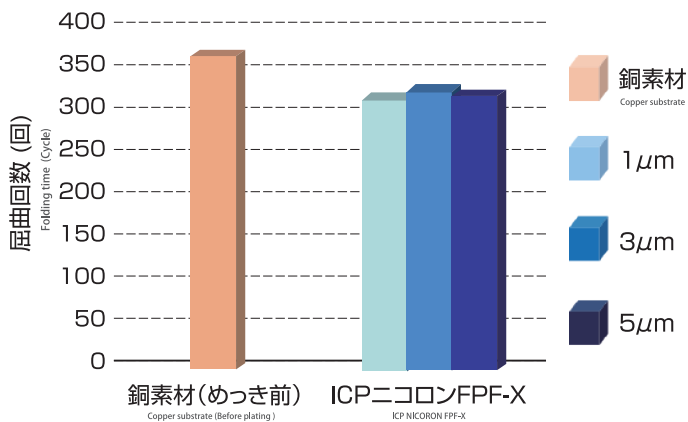
金剥離後ニッケル皮膜表面
Nickel film surface (After peeling gold film)

金めっきによる腐食の低減

Reduce nickel film damage by gold plating

優れた耐折性

Excellent folding endurance



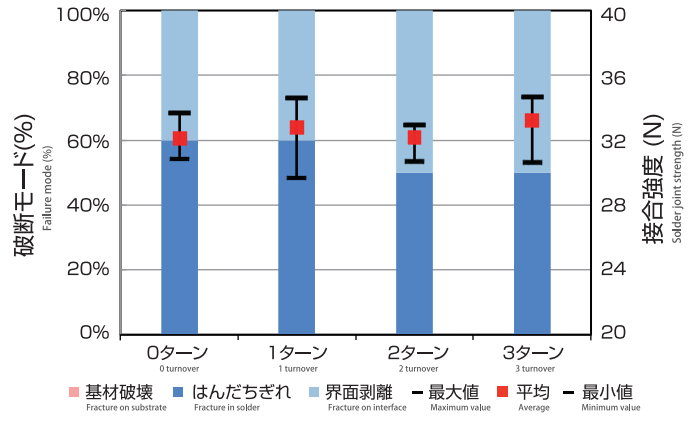
MIT試験 MIT folding endurance test

めっき厚さに関わらず良好な耐折性

Excellent in folding endurance performance regardless of film thickness

良好なはんだ接合強度

Excellent in solder joint performance



はんだプル強度試験 Solder pull strength test

連続使用においても良好な接合性

Excellent in solder joint performance in continuous use